• Matched to Broadcom BCM6410 & BCM6420 Chipsets
• EN60950 Basic Insulation compliant 250Vrms
• SMD compact footprint design
• Industrial operating temp: -40°C to +85°C

### Electrical Specifications @25°C

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Turns Ratio (10KHz,0.1V)</th>
<th>OCL (10KHz,0.1V)</th>
<th>LL (100KHz,0.1V)</th>
<th>Cww (100KHz,0.1V)</th>
<th>DCR</th>
<th>THD</th>
<th>LB</th>
<th>Hi-Pot VAC</th>
</tr>
</thead>
<tbody>
<tr>
<td>AEP001SI</td>
<td>1-8-6 (short 2-3,5-7-8)</td>
<td>1-4 (short 2-3)</td>
<td>1-8 (short 2-3, 5-6-7-8)</td>
<td>1-4 (short 2-3)</td>
<td>8-6 (short 5-7)</td>
<td>(30KHz,3.16Vrms)</td>
<td>(2.2MHz) (0.5mA/60s)</td>
<td></td>
</tr>
<tr>
<td></td>
<td>1.2:1±2%</td>
<td>430uH±6%</td>
<td>4uH max</td>
<td>35pF max</td>
<td>1.3Ω max</td>
<td>1.0Ω max</td>
<td>-78dB max</td>
<td>55dB min</td>
</tr>
</tbody>
</table>

All specifications subject to change without notice.

### MECHANICAL

SUGGESTED PAD LAYOUT

Units:mm

Unless otherwise specified all tolerances are: ±0.25 in mm

### SCHEMATICS

LINE

CHIP